#### **Gas Pixel Detectors**

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### Polarimetry: The Missing Piece of the Puzzle

#### Imaging: Chandra

#### Timing: RXTE



#### Spectroscopy: AstroE2, Constellation-X, Chandra

**Polarimetry: ?** 

### The only polarized source already known

p.s.f.





Positive measurement: of X-ray polarization of the Crab Nebula without pulsar contamination (by lunar occultation, Weisskopf et al., 1978). P = 19.2 ± 1.0 %  $\theta = 156.4^{\circ} \pm 1.4^{\circ}$ 

But this is only the average measurement.The structure is much more complex!

**PSR** NW jet SE jet **Inner torus Outer torus** 

With XPOL we can perform the separate polarimetry, imaging, spectroscopy and timing of details of the major structures

# **Photoelectric cross section**

#### The photoelectric effect is very sensitive to photon polarization!



Simple analytical expression for photoemission differential cross section (k-shell photoelectron in non-relativistic limit):

$$\frac{\partial \sigma}{\partial \Omega} = r_o^2 \frac{Z^5}{137^4} \left(\frac{mc^2}{hv}\right)^{\frac{1}{2}} \frac{4\sqrt{2}\sin^2(\theta)\cos^2(\phi)}{(1-\beta\cos(\theta))^4}$$

If we project on the plane orthogonal to the propagation direction...

$$\frac{\partial \sigma}{\partial \Omega} \propto \cos^2 \phi$$

### Photoelectron and Auger angular distributions











Auger emission directions Photoelectron emission directions

# The principle of detection





A custom CMOS analog chip is at the same time the pixelized charge collecting electrode and the amplifying, shaping and charge measuring front-end electronics of Micropattern Gas Detectors (MPGD) or other suitable charge multiplier



three ASIC generations of increasing size, reduced pitch and improved functionality have been realized

### The collecting anode/read-out VLSI chip

# First ASIC prototype

#### Advantages: asynchronous, fast, low noise

pixel electronics dimension: **30** μm x **30** μm in an hexagonal array, **comprehensive** of preamplifier/shaper, S/H and routing (serial read-out) for each pixel number of pixels: 2101

TICHTICARD AL

~3.5 μs shaping time
100 e- ENC
100 mv/fC input sensitivity
20 fC dynamic range



# Tracks reconstruction

1) The track is recorded by the PIXel Imager

#### 2) Baricenter evaluation

3) Reconstruction of the principal axis of the track: maximization of the second moment of charge distribution

4) Reconstruction of the conversion point: major second moment (track length) + third moment along the principal axis (asymmetry of charge release)

5) Reconstruction of emission direction: pixels are weighted according to the distance from conversion point.



# From 2k to 22k pixels







# Further technological step: a 0.18 μm CMOS VLSI



The chip integrates more than 16.5 million transistors. It has a15mm x 15mm active area of 105'600 pixels organized in a honeycomb matrix

470 pixels/mm<sup>2</sup>

 $\begin{array}{l} \mbox{Matrix organization} \\ 300 \mbox{(width=300x50 $\mu$m=15mm) $x$ 352 \mbox{(height=352x43.3 $\mu$m=15.24mm) $pixels$} \\ 16 \mbox{ clusters of 300 $x$ 22 = 6600 $pixels each or} \\ 8 \mbox{ clusters of 300 $x$ 44 = 13200 $pixels each} \end{array}$ 

# 0.18 µm ASIC features

- Peaking time: 3-10 μs, externally adjustable;
- Read-out clock: up to 10MHz;
- Frame rate: up to 10 kHz in self-trigger mode (event window);
- Read-out mode: asynchronous or synchronous;
- Trigger mode: intenal, external or self-trigger;
- Pixel noise: 50 electrons ENC;
- Self-trigger threshold: 2300 electrons;
- Full-scale linear range: 30000 electrons;
- Parallel analog output buffers: 1, 8 or 16;
- Access to pixel content: direct (single pixel) or serial (8-16 clusters, full matrix, region of interest);
- (o-to clusters, full matrix, region of interest);
- Fill fraction (ratio of metal area to active area): 92%

Total power dissipation ~ 0.5 Watt

# Self-trigger functionality





 ✓ charge sum of mini-cluster of 4 pixels contribute to a <u>local</u> trigger with dedicated s.a.
 ✓ threshold < 3000 e<sup>-</sup> (10% FS)

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- ✓ individual pixel trigger mask

✓ independent trigger level for each 16 clusters

 ✓ event localization in rectangle containing all triggered mini-clusters + user selectable region of 10 or 20 pixels

 ✓ the chip calculates the event ROI (X<sub>min</sub>, Y<sub>min</sub> – X<sub>max</sub>, Y<sub>max</sub>) for subsequent sequential readout of selected area



# Noise and threshold



# **Detector** assembly



1 - The GEM glued to the bottom of the gas-tight enclosure2 - The large area ASIC mounted on the control motherboard

Large effective gas gain around 1000 @450V in Ne(50%)-DME(50%) (at least 70 V less than in our standard 90 μm pitch GEM)

#### GEM specs pitch: 50 μm holes **outer Ø: 35 μm**



The matching of readout and gas amplification (GEM) pitch allows getting optimal results and to fully exploit the very high granularity of the device

# The read-out system



# **On-line monitoring**



#### **Real time pedestal subtraction**

# Imaging capability



#### <sup>55</sup>Fe source Ne(50%)-DME(50%)



Holes: 0.6 mm diameter, 2 mm apart.

# Imaging and spectroscopic capability

#### Argon (50%)-DME(50%)

Baricenter position





Holes: Ø 0.5 mm pitch 1 mm

# Polarizing X-rays



#### 90° Thompson scattering



# Track morphology and angle reconstruction



Event Number:	101
Number of Clusters:	1
Cluster Size (largest):	130
Pulse Height:	12208.2
Signal to Noise:	320.1
Baricenter:	2.50 -4.31
Conversion Point:	2.38 -4.01
Second Mom Max:	0.0459
Second Mom Min:	0.0134
Shape (ratio of moments):	3.42
Third Mom Max:	-2.6e-03
Phi (iteration 1)	-0.9540
Phi (iteration 2)	-1.8518

Reconstructed Baricenter
 Reconstructed Impact Pt.

Event Number:	25
Number of Clusters:	1
Cluster Size (largest):	121
Pu'^e Height:	10625.1
Signal to Noise:	278.9
Baricenter:	-0.15 2.95
Conversion Point:	-0.63 2.94
Second Mom Max:	0.0475
Second Mom Min:	0.0210
Shape (ratio of moments):	2.26
Third Mom Max:	-1.1e-02
Phi (iteration 1)	0.1949
Phi (iteration 2)	-0.2401

↔ Reconstructed Baricenter
 ↔ Reconstructed Impact Pt.

# **Modulation factor**

#### Measured with two different gas mixtures: He/DME and Ne/DME



# **Residual modulation**



S/N distribution, scatter plot of the two principal axes of the cluster charge and residual modulation, obtained with <sup>55</sup>Fe source in Ne(50%)-DME(50%)

### **Expected MDP with XEUS optics** @ different source fluxes and spectral index



#### | He(40%)-DME(60%)

With observations of one day we can measure the polarization of several AGNs down to 1 % for 1 mCrab flux

# With 1 h it is possible to get few % with a 10 mCrab flux

Ne(50%)-DME(50%)



# Conclusions

With devices like the one presented the class of Gas Pixel Detectors has reached the level of integration, compactness and resolving power typical of solid state detectors.

Depending on type of electron multiplier, pixel and die size, electronics shaping time, analog vs. digital read-out, counting vs. integrating mode, many applications can be envisaged for this class of detectors.

As for the X-ray polarimetry applications a residual modulation very low and a modulation factor well above 50% will likely allow polarimetric measurements at the level of ~1% for hundreds of galactic and extragalactic sources.

*A real breakthrough in X-ray astronomy* if compared with the traditional X-ray polarimeters sensitivity.



An efficient photoelectric X-ray polarimeter for the study of black holes and neutron stars

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